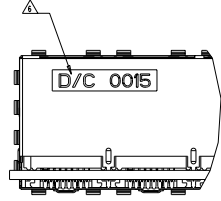
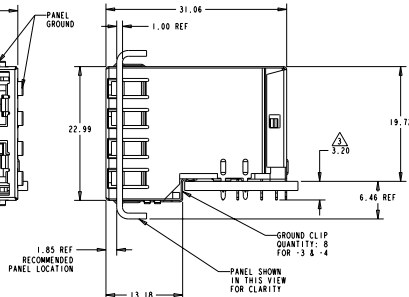
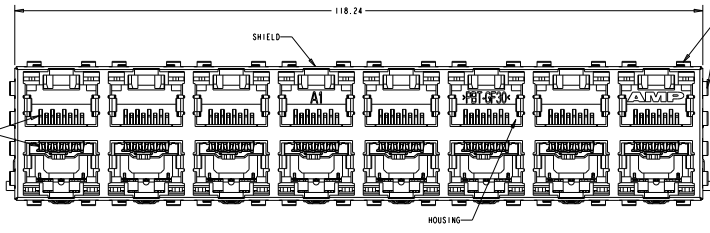
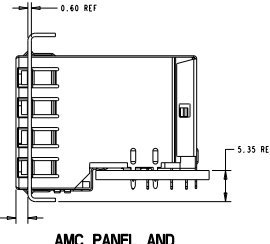


REVISONS		DATE	BY	APP
A	RELEASED		DMC/DMN	JW
B	ECO-07-001858		DMC/DMN	JW
C	ECO-08-019486		DMC/DMN	A.L. S.T



ATCA PANEL AND PRINTED CIRCUIT BOARD ASSEMBLY LAYOUT

- MATERIAL:**
 HOUSING: 90T POLYESTER, BLACK, UL 94V-0
 TERMINALS:
 0.33 THICK PHOSPHOR BRONZE PLATED WITH 1.27µm MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 2.0µm MINIMUM THICK MATTE TIN IN COMPLIANT PIN TERMINAL AREA OVER 1.27µm MINIMUM THICK NICKEL UNDERPLATE
 SHIELD:
 0.25 THICK COPPER ALLOY PLATED WITH 2.03µm MINIMUM TIN OVER 1.27µm MINIMUM NICKEL
 GROUND CLIP: 0.25 THICK COPPER ALLOY PRE-PLATED WITH 2.03µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL
 - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68
- ⚠ MAXIMUM PIN LENGTH 3.40 FROM TOP SURFACE OF PC BOARD
 - ⚠ FINISHED PLATED THROUGH HOLE DIAMETER - ANNULAR RING DIAMETER 1.3 TO 1.5
 - ⚠ DATUMS AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
 - ⚠ DATE CODE LOCATED ON REAR OF PART APPROXIMATELY AS SHOWN
 - ⚠ CONTACTS ARE NOT INTENDED TO BE ALIGNED WITH EACH OTHER



AMC PANEL AND PRINTED CIRCUIT BOARD ASSEMBLY LAYOUT

M D I M	DESCRIPTION	PART NUMBER
15.88	WITH GROUND CLIP	1888654-4
15.88	WITH GROUND CLIP	1888654-3 (SHOWN)
16.13	WITHOUT GROUND CLIP	1888654-2
16.13	WITHOUT GROUND CLIP	1888654-1

DATE: 08/14/12 DRAWN BY: J. WILSON CHECKED BY: J. WILSON DATE: 08/14/12 APPROVED BY: J. WILSON DATE: 08/14/12	DATE: 08/14/12 DRAWN BY: J. WILSON CHECKED BY: J. WILSON DATE: 08/14/12 APPROVED BY: J. WILSON DATE: 08/14/12	DATE: 08/14/12 DRAWN BY: J. WILSON CHECKED BY: J. WILSON DATE: 08/14/12 APPROVED BY: J. WILSON DATE: 08/14/12	DATE: 08/14/12 DRAWN BY: J. WILSON CHECKED BY: J. WILSON DATE: 08/14/12 APPROVED BY: J. WILSON DATE: 08/14/12
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TERA ELECTRONICS CORPORATION
 HARRISBURG, PA 17105-3600
 STACKED MOD JACK ASSEMBLY, 2 X 8, 8 POSN, SHIELDED, PANEL GROUND, OFFSET, CAT 5
 STATE: PA
 DATE CODE (DATE) 00
 PART NUMBER 1888654
 CUSTOMER DRAWING
 SHEET 1 OF 2

